# **DATA SHEET**



# MOS FIELD EFFECT TRANSISTOR **2SK2485**

# SWITCHING **N-CHANNEL POWER MOS FET INDUSTRIAL USE**

## DESCRIPTION

The 2SK2485 is N-Channel MOS Field Effect Transistor designed www.DataSheet4U.comfor high voltage switching applications.

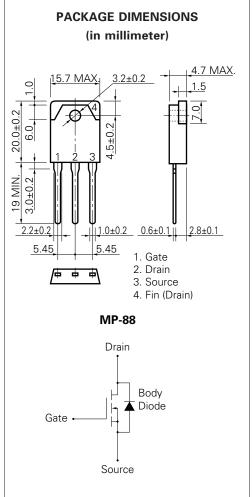
#### **FEATURES**

- Low On-Resistance
  - RDS (on) =  $2.8 \Omega$  (VGS = 10 V, ID = 3.0 A)
- Low Ciss Ciss = 1 200 pF TYP.
- High Avalanche Capability Ratings

#### ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

Drain to Source Voltage	Vdss	900	V
Gate to Source Voltage	Vgss	±30	V
Drain Current (DC)	D (DC)	±6.0	А
Drain Current (pulse)*	D (pulse	e) ±12	А
Total Power Dissipation (T <sub>c</sub> = 25 $^{\circ}$ C)	Pt1	100	W
Total Power Dissipation (T <sub>A</sub> = 25 $^{\circ}$ C)	Рт2	3.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	–55 to +150	°C
Single Avalanche Current**	las	6.0	А
Single Avalanche Energy**	Eas	42.3	mJ
* PW $\leq$ 10 $\mu$ s, Duty Cycle $\leq$ 1 %			

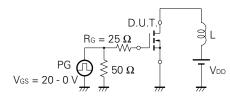
\*\* Starting T<sub>ch</sub> = 25 °C, R<sub>G</sub> = 25  $\Omega$ , V<sub>GS</sub> = 20 V  $\rightarrow$  0

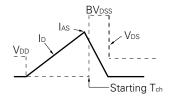


ELECTRICAL	CHARACTERISTICS	(T <sub>A</sub> = 25 °C)
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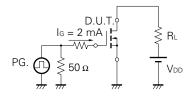
CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain to Source On-Resistance	RDS (on)		2.2	2.8	Ω	$V_{GS} = 10 \text{ V}, \text{ Id} = 3.0 \text{ A}$
Gate to Source Cutoff Voltage	VGS (off)	2.5		3.5	V	Vds = 10 V, Id = 1 mA
Forward Transfer Admittance	y <sub>fs</sub>	2.0			S	Vds = 10 V, Id = 3.0 A
Drain Leakage Current	Ibss			100	μA	Vds = Vdss, Vgs = 0
Gate to Source Leakage Current	Igss			±100	nA	$V_{GS} = \pm 30 \text{ V}, \text{ V}_{DS} = 0$
Input Capacitance	Ciss		1200		pF	Vds = 10 V
Output Capacitance	Coss		170		pF	V <sub>GS</sub> = 0
Reverse Transfer Capacitance	Crss		30		pF	f = 1 MHz
eei₄Turn⊤On Delay Time	td (on)		20		ns	ID = 3.0 A
Rise Time	tr		10		ns	Vgs = 10 V
Turn-Off Delay Time	td (off)		70		ns	Vdd = 150 V
Fall Time	tr		15		ns	$R_G = 10 \ \Omega R_L = 50 \ \Omega$
Total Gate Charge	QG		40		nC	ID = 6.0 A
Gate to Source Charge	Qgs		7		nC	V <sub>DD</sub> = 450 V
Gate to Drain Charge	Qgd		17		nC	Vgs = 10 V
Body Diode Forward Voltage	VF (S-D)		1.0		V	IF = 6.0 A, VGS = 0
Reverse Recovery Time	trr		740		ns	IF = 6.0 A, VGS = 0
Reverse Recovery Charge	Qrr		4.0		μC	di/dt = 50 A/µs

#### Test Circuit 1 Avalanche Capability

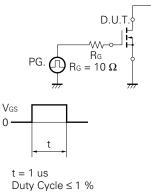


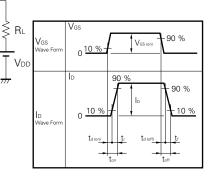


#### Test Circuit 3 Gate Charge

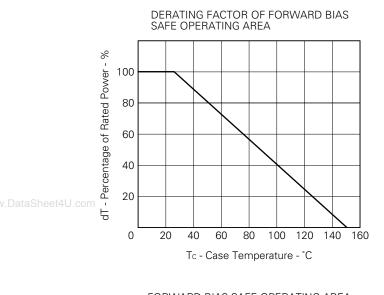


#### Test Circuit 2 Switching Time

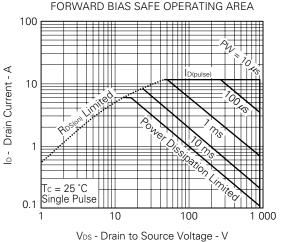




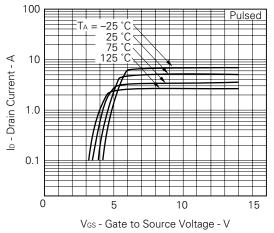
The application circuits and their parameters are for references only and are not intended for use in actual design-in's.

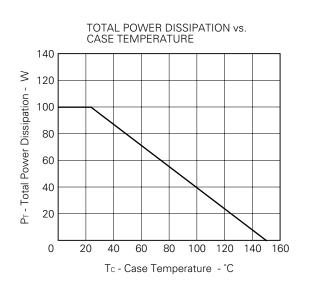


TYPICAL CHARACTERISTICS ( $T_A = 25$  °C)

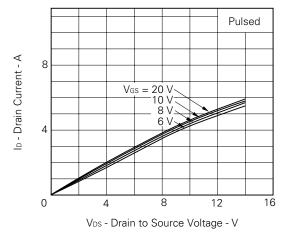


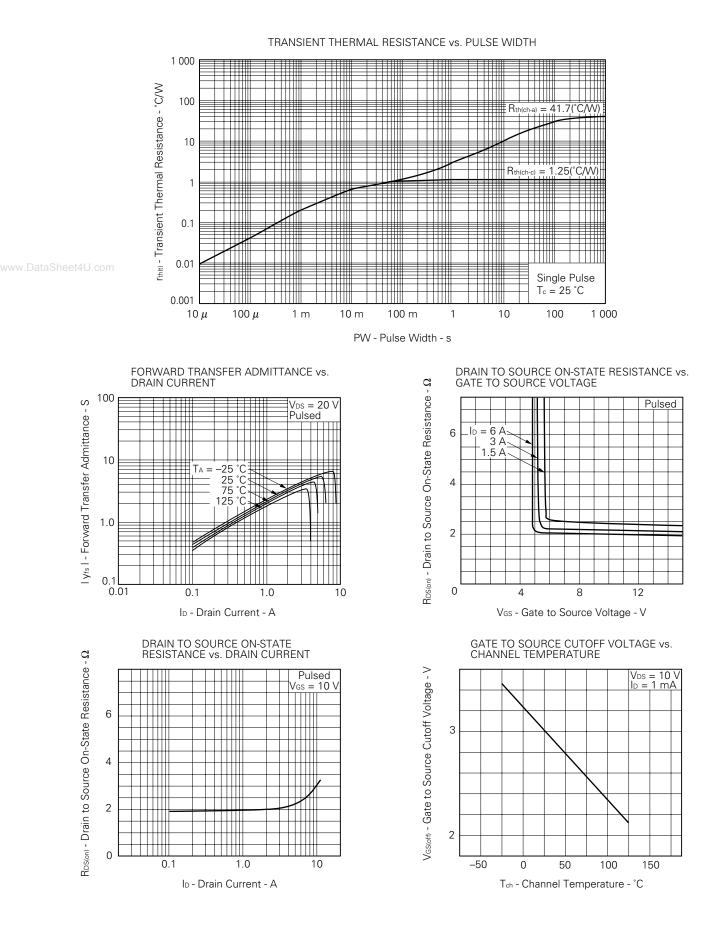


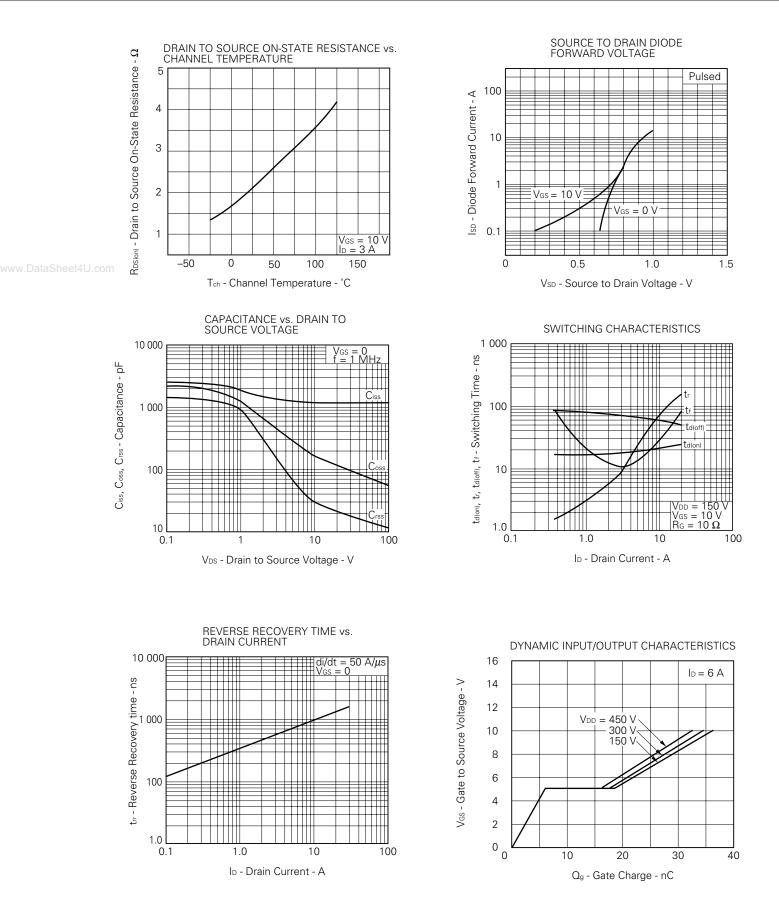


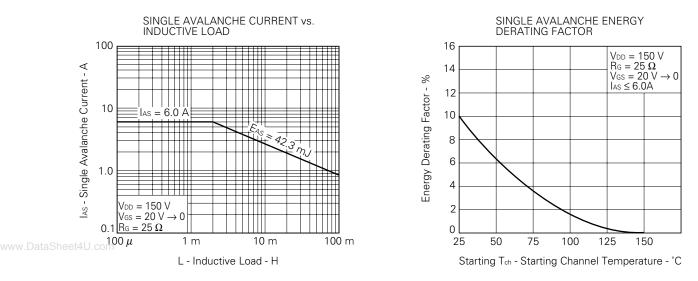












### REFERENCE

Document Name	Document No.
NEC semiconductor device reliability/quality control system.	TEI-1202
Quality grade on NEC semiconductor devices.	IEI-1209
Semiconductor device mounting technology manual.	IEI-1207
Semiconductor device package manual.	IEI-1213
Guide to quality assurance for semiconductor devices.	MEI-1202
Semiconductor selection guide.	MF-1134
Power MOS FET features and application switching power supply.	TEA-1034
Application circuits using Power MOS FET.	TEA-1035
Safe operating area of Power MOS FET.	TEA-1037

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Anti-radioactive design is not implemented in this product.

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